

**CALL FOR PAPERS**

2023 International Conference on Big Data and Smart Computing

February 13(Mon.)-16(Thu.), 2023, MasonGlad Hotel, Jeju, Korea

<https://bigcomputing.org>

Big data and smart computing are emerging research fields that have been drawing much attention from diverse disciplines including computer science, information technology, and social sciences. The goal of the International Conference on Big Data and Smart Computing (BigComp), initiated by KIISE (Korean Institute of Information Scientists and Engineers), is to provide an international forum for exchanging ideas and information on current studies, challenges, research results, system developments, and practical experiences in these emerging fields among researchers, developers, and users from academia, business and industry. Following the successes of the previous BigComp conferences in Bangkok, Thailand (2014), Jeju, Korea (2015), Hong Kong, China (2016), Jeju, Korea (2017), Shanghai, China (2018), Kyoto, Japan (2019), Busan, Korea (2020), Jeju, Korea (2021), and Daegu, Korea (2022), the 2023 IEEE International Conference on Big Data and Smart Computing (IEEE BigComp 2023) will be held in Jeju, Korea. The conference is co-sponsored by IEEE and KIISE. IEEE BigComp 2023 invites authors to submit original research papers and as well original work-in-progress reports on big data and smart computing.

BigComp 2023 will be held in Jeju, Korea. Jeju island, centred with the Halla Mountain, is one of the most exceptional islands in the world to enjoy various outdoor activities as well as a variety of dining options. Jeju International Airport is connected with over 100 flights per day from Seoul and is also linked with over 50 direct flights per day to international destinations in China, Japan, Taiwan, Hong Kong, Thailand and Malaysia. The conference venue, MasonGlad hotel, is only 10 minutes away by a taxi from the Jeju airport.

For more information about Jeju, see <https://www.visitjeju.net/en/>.

TOPICS of interest: We invite the submission of original research contributions in the following areas, but also welcome any original contributions that may cross the boundaries among areas or point in other novel directions. In addition, BigComp 2023 encourages submissions about products, practices, and services in industry:

- Big data analytics and social media
- Big data applications / big data as a service
- Big data ecosystem
- Bioinformatics, multimedia, smartphones, etc.
- Cloud and grid computing for big data
- Crowdsourcing and human-in-the-loop
- Data mining and data science
- Data and information quality
- Disaster analysis
- Infrastructure and platform for big data and smart computing
- Knowledge graph, graph data management and mining
- Machine learning and AI for big data
- Machine learning and AI theory and fundamentals
- Mobile communications and smart location-based services
- Recommender systems
- Search/retrieval and generation of big data
- Security and privacy for big data
- Smart computing models, tools, and devices
- Techniques, models and algorithms for big data
- Tools and systems for big data
- Understanding multi-modal data

IMPORTANT DATES

- Paper submission: ~~October 14, 2022~~ → **October 28, 2022**
- Tutorial/Workshop proposal: ~~September 30, 2022~~ → **October 7, 2022**
- Notification of acceptance: **November 30, 2022**
- Camera-ready: **December 20, 2022**
- Early registration: **January 23, 2023**

PAPER SUBMISSION

Original papers formatted in PDF according to the IEEE two-column format for conference proceedings must be submitted through EasyChair. Regular papers are limited to 8 pages and short ones to 4 pages. BigComp 2023 adopts double-blind review policy. For details, please see the submission guideline at the conference homepage.

General Co-Chairs

- Hyeran Byun (Yonsei University, Korea)
- Beng Chin Ooi (National University of Singapore, Singapore)
- Katsumi Tanaka (Kyoto University / University of Fukuchiyama, Japan)

Organization Co-Chairs

- Wen-Huang Cheng (National Chiao Tung University, Taiwan)
- Jae-Gil Lee (KAIST, Korea)

Program Committee Co-Chairs

- Sang-Won Lee (Sungkyunkwan University, Korea)
- Zhixu Li (Fudan University, China)
- Akiyo Nadamoto (Konan University, Japan)
- Giltae Song (Pusan National University, Korea)

Workshop Co-Chairs

- Young-guk Ha (Konkuk University, Korea)
- Kazutoshi Sumiya (Kwansei Gakuin University, Japan)
- Wu Yuncheng (National University of Singapore, Singapore)

Tutorial Chairs

- Makoto Kato (University of Tsukuba, Japan)
- Se-Young Yun (KAIST, Korea)

Panel Co-Chairs

- Anh Dinh (Singapore University of Technology and Design, Singapore)
- Yoshiyuki Shoji (Aoyama Gakuin University, Japan)
- Jinyoung Yeo (Yonsei University, Korea)

Finance Co-Chairs

- Hiroaki Ohshima (University of Hyogo, Japan)
- Noseong Park (Yonsei University, Korea)

Publicity Co-Chairs

- Hyunjung Shin (Ajou University, Korea)
- Yusuke Yamamoto (Shizuoka University, Japan)
- Bolong Zheng (HUST, China)

Local Arrangement Co-Chair

- Yungcheol Byun (Jeju National University, Korea)

Publication Co-Chairs

- Hyuk-Yoon Kwon (Seoul Natl' Univ. of Science and Technology, Korea)
- Takehiro Yamamoto (University of Hyogo, Japan)

Registration & Web Co-Chair

- Byoung Chul Ko (Keimyung University, Koera)